

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Council of	Fusition a Colon	Value		Unit
Parameter	Symbol	Emitting Color	Тур.	Тур. Мах.	Unit
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Super Bright Yellow	590	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Super Bright Yellow	590	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Super Bright Yellow	20	-	nm
Capacitance	С	Super Bright Yellow	20	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Super Bright Yellow	2.0	2.5	V
Reverse Current (V _R = 5V)	I _R	Super Bright Yellow	-	10	μΑ
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq 85^{\circ}C$	$TC_{\lambda peak}$	Super Bright Yellow	0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C $\leq T \leq 85^{\circ}C$	TC_{\lambdadom}	Super Bright Yellow	0.07	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TC _V	Super Bright Yellow	-1.9	-	mV/°C

Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ± 1 nm.)

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit
Power Dissipation	P_{D}	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	Tj	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T_{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	175	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	670	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} [2]	540	°C/W

Tules.

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).

3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

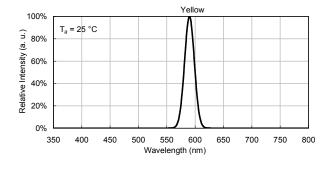


^{2.} Forward voltage: £0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

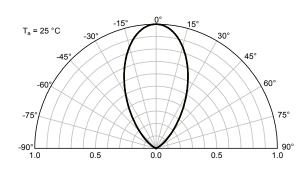


TECHNICAL DATA

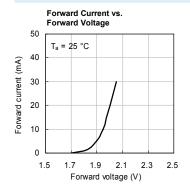
RELATIVE INTENSITY vs. WAVELENGTH

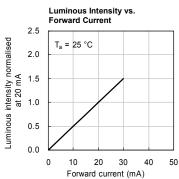


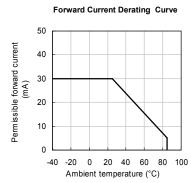
SPATIAL DISTRIBUTION

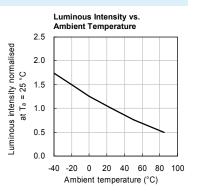




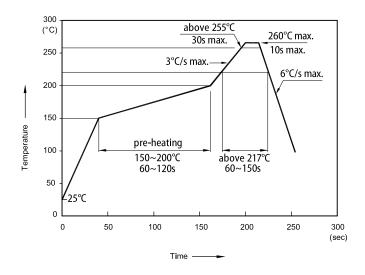






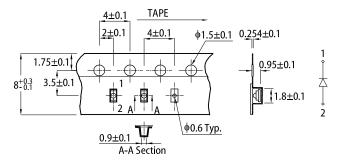


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

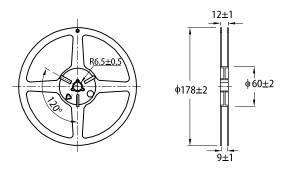


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units: mm)



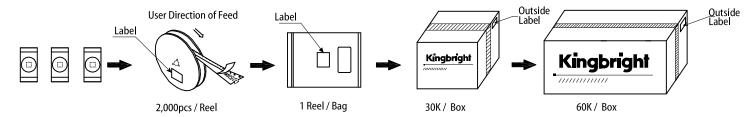
REEL DIMENSION (units: mm)

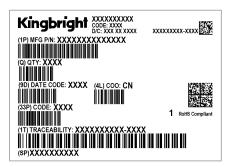






PACKING & LABEL SPECIFICATIONS





PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.

 When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- toustomer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
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